



#### 60V +175°C N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI5060-8

## **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D MAX</sub> T <sub>C</sub> = +25°C	
60V	$8m\Omega$ @ $V_{GS} = 10V$	80A	
607	$12m\Omega$ @ $V_{GS} = 4.5V$	64.5A	

## **Features**

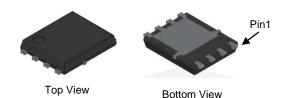
- Rated to +175°C Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching (UIS) Test in Production— Ensures More Reliable and Robust End Application
- Low R<sub>DS(ON)</sub>—Minimizes On State Losses
- Low Input Capacitance
- Fast Switching Speed
- Wettable Flank for Improved Optical Inspection
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMTH6010LPSWQ is suitable for automotive applications requiring specific change control and is AEC-Q101 qualified, is PPAP capable, and is manufactured in IATF16949:2016 certified facilities.

## **Description and Applications**

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP, and is ideal for use in:

- Engine Management Systems
- Body Control Electronics
- DC-DC Converters

PowerDI5060-8 (SWP) (Type Q)



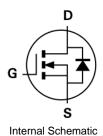
#### **Mechanical Data**

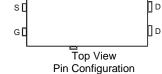
- Case: PowerDI<sup>®</sup>5060-8
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish—Matte Tin Annealed over Copper Leadframe;
   Solderable per MIL-STD-202, Method 208 (3)

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Weight: 0.097 grams (Approximate)





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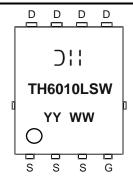
Ordering Information (Note 4)

Part Number	Case	Packaging
DMTH6010LPSWQ-13	PowerDI5060-8 (SWP) (Type Q)	2500 / Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

### **Marking Information**



DIII = Manufacturer's Marking
TH6010LSW = Product Type Marking Code
YYWW = Date Code Marking
YY = Last Two Digits of Year (ex: 19 = 2019)
WW = Week Code (01 to 53)



# **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	$V_{DSS}$	60	V		
Gate-Source Voltage		$V_{GSS}$	±20	V	
Continuous Prain Current V 40V/Note 5V	$T_A = +25$ °C	l <sub>D</sub>	15.5	^	
Continuous Drain Current, V <sub>GS</sub> = 10V (Note 5)	T <sub>A</sub> = +100°C		11	A	
Continuous Prain Current V 40V/Note 6)	$T_C = +25^{\circ}C$	I <sub>D</sub>	80	A	
Continuous Drain Current, V <sub>GS</sub> = 10V (Note 6)	T <sub>C</sub> = +100°C		56		
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I <sub>DM</sub>	320	А		
Maximum Continuous Body Diode Forward Current (Note 6)	I <sub>S</sub>	80	A		
Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle	I <sub>SM</sub>	320	A		
Avalanche Current, L=0.1mH	I <sub>AS</sub>	20	A		
Avalanche Energy, L=0.1mH	E <sub>AS</sub>	20	mJ		

# **Thermal Characteristics**

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	T <sub>A</sub> = +25°C	$P_{D}$	2.9	W
Thermal Resistance, Junction to Ambient (Note 5)		$R_{\theta JA}$	52	°C/W
Total Power Dissipation (Note 6)	T <sub>C</sub> = +25°C	$P_{D}$	75	W
Thermal Resistance, Junction to Case (Note 6)		$R_{\theta JC}$	2.0	°C/W
Operating and Storage Temperature Range		$T_{J}$ , $T_{STG}$	-55 to +175	°C

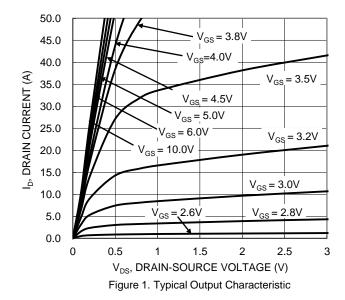
## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	60	_	_	V	$V_{GS} = 0V, I_D = 1mA$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	1	μA	V <sub>DS</sub> = 48V, V <sub>GS</sub> = 0V	
Gate-Source Leakage	I <sub>GSS</sub>	_		±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	1	_	3	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance			5.3	8	mΩ	$V_{GS} = 10V, I_D = 20A$	
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	_	7.9	12	11122	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 20A	
Diode Forward Voltage	V <sub>SD</sub>	_	0.8	1.2	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = 20A	
DYNAMIC CHARACTERISTICS (Note 8)		•			•		
Input Capacitance	C <sub>iss</sub>	_	2090	_		$V_{DS} = 30V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Output Capacitance	Coss	_	746	_	pF		
Reverse Transfer Capacitance	C <sub>rss</sub>	_	38.5	_			
Gate Resistance	R <sub>g</sub>	_	0.59	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg	_	19.3	_			
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg	_	41.3	_	nC	V <sub>DS</sub> = 30V, I <sub>D</sub> = 20A	
Gate-Source Charge	Q <sub>gs</sub>	_	6	_	110		
Gate-Drain Charge	$Q_{gd}$	_	8.8	_			
Turn-On Delay Time	t <sub>D(ON)</sub>	_	5.7	_			
Turn-On Rise Time	t <sub>R</sub>	_	4.3	_	ns	$V_{DD} = 30V, V_{GS} = 10V,$ $I_{D} = 20A, R_{g} = 3\Omega$	
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	23.4	_	115		
Turn-Off Fall Time	t <sub>F</sub>	_	9.7	_			
Body Diode Reverse Recovery Time	t <sub>RR</sub>	_	35.4	_	ns	1 20A di/dt 100A/vo	
Body Diode Reverse Recovery Charge	Q <sub>RR</sub>	_	38.2	_	nC	I <sub>F</sub> = 20A, di/dt = 100A/μs	

Notes:

- 5. Device mounted on FR-4 substrate PCB, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
- Thermal resistance from junction to soldering point (on the exposed drain pad).
   Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to product testing.





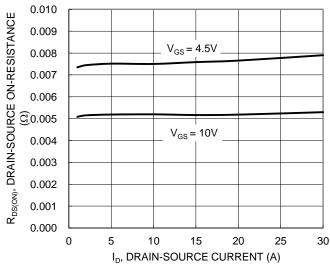


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

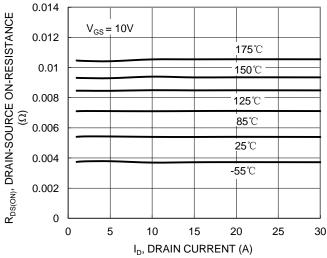


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

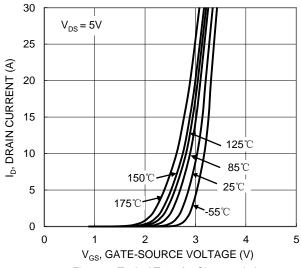


Figure 2. Typical Transfer Characteristic

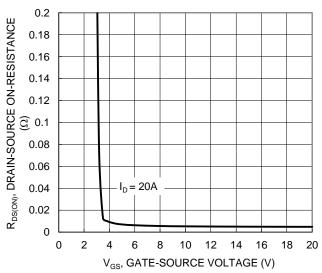


Figure 4. Typical Transfer Characteristic

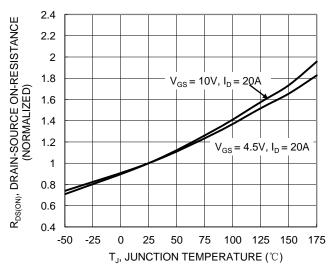


Figure 6. On-Resistance Variation with Temperature



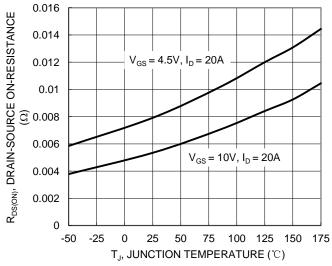


Figure 7. On-Resistance Variation with Temperature

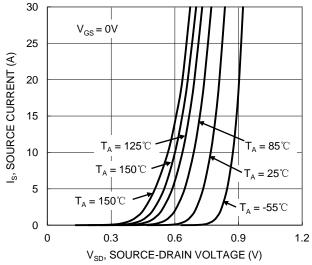
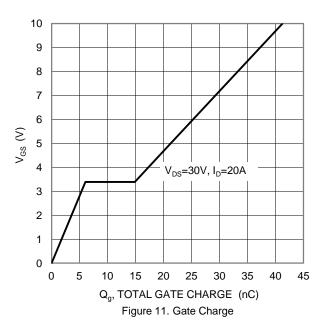


Figure 9. Diode Forward Voltage vs. Current



3  $V_{GS(TH)},$  GATE THRESHOLD VOLTAGE (V) 2.5  $I_D = 1 \text{mA}$ 2 1.5  $I_{D} = 250 \mu A$ 1 0.5 0 -50 -25 0 25 50 75 100 125 150 175  $T_J$ , JUNCTION TEMPERATURE ( $^{\circ}$ C)

Figure 8. Gate Threshold Variation vs. Junction Temperature

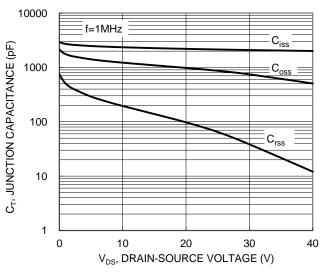
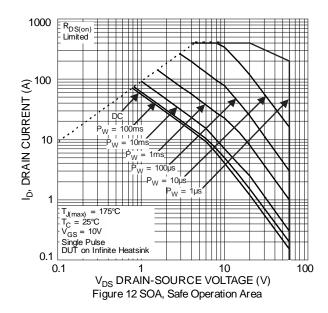


Figure 10. Typical Junction Capacitance





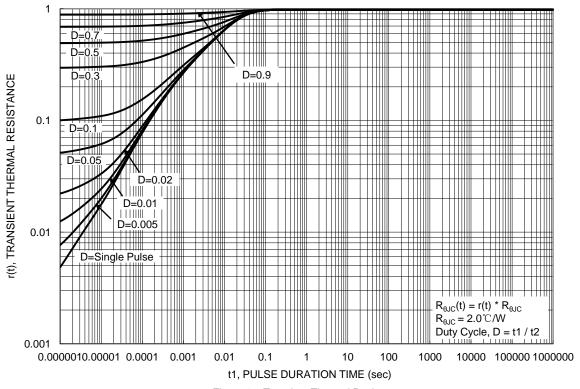


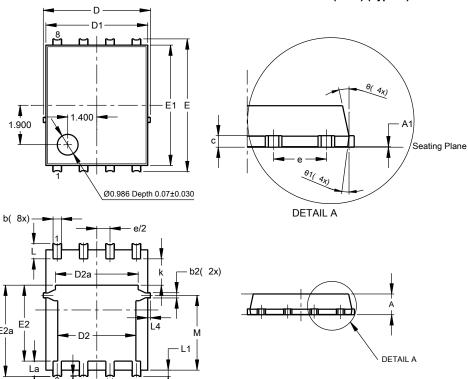
Figure 13. Transient Thermal Resistance



## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI5060-8 (SWP) (Type Q)

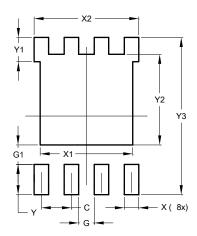


PowerDI5060-8 (SWP)					
(Type Q)					
Dim	Min	Max	Тур		
Α	0.90	1.10	1.00		
<b>A</b> 1	0	0.05			
b	0.30	0.50	0.41		
b2	0.20	0.35	0.25		
b4		).25REF			
С	0.230	0.330	0.277		
D	5	.15 BS0	)		
D1	4.70	5.10	4.90		
D2	3.56	3.96	3.76		
D2a	3.78	4.18	3.98		
Е	6	.40 BS0	)		
E1	5.60	6.00	5.80		
E2	3.46	3.86	3.66		
E2a	4.195	4.595	4.395		
е	1	.27BSC	;		
k	1.05				
L	0.635	0.835	0.735		
La	0.635	0.835	0.735		
L1	0.200	0.400	0.300		
L1a	0.050REF				
L4	0.025	0.225	0.125		
M	3.205	4.005	3.605		
θ	10°	12°	11°		
θ1	6°	8°	7°		
All Dimensions in mm					

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### PowerDI5060-8 (SWP) (Type Q)



Dimensions	Value (in mm)		
С	1.270		
G	0.660		
G1	0.820		
Х	0.610		
X1	4.100		
X2	4.420		
Y	1.270		
Y1	1.020		
Y2	3.810		
Y3	6.610		



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